

UNISONIC TECHNOLOGIES CO., LTD

8N80 Preliminary Power MOSFET

800V N-CHANNEL MOSFET

DESCRIPTION

The UTC **8N80** is an N-channel mode Power FET, it uses UTC's advanced technology to provide costumers planar stripe and DMOS technology. This technology allows a minimum on-state resistance, superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

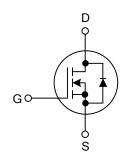
The UTC **8N80** is generally applied in high efficiency switch mode power supplies.

■ FEATURES

- * Typically 35 nC Low Gate Charge
- * 8A, 800V, $R_{DS(on)} = 1.55\Omega @V_{GS} = 10 V$
- * Typically 13 pF Low Crss
- * Improved dv/dt Capability
- * Fast Switching Speed
- * 100% Avalanche Tested
- * RoHS-Compliant Product

TO-220F1

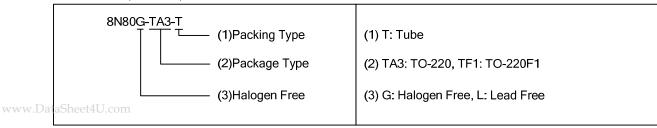
■ SYMBOL



■ ORDERING INFORMATION

Ordering Number		Dookogo	Pin Assignment			Dooking	
Lead Free	Halogen Free	- Package	1	2	3	Packing	
8N80L-TA3-T	8N80G-TA3-T	TO-220	G	D	S	Tube	
8N80L-TF1-T	8N80G-TF1-T	TO-220F1	G	D	S	Tube	

Note: G: GND, D: Drain, S: Source



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■ ABSOLUTE MAXIMUM RATINGS (T_C=25°C, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	V_{DSS}	800	V
Gate-Source Voltage	V_{GSS}	±30	V
Drain Current (Continuous) (T _C =25°C)	I_D	8	Α
Drain Current (Pulsed) (Note 1)	I_{DM}	32	Α
Avalanche Current (Note 1)	I _{AR}	8	Α
Single Pulse Avalanche Energy (Note 2)	E _{AS}	850	mJ
Repetitive Avalanche Energy (Note 1)	E _{AR}	17.8	mJ
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5	V/ns
Total Power Dissipation (T _C =25°C)	P _D	178	W
Linear Derating Factor above T _C =25°C	FD	1.43	W/°C
Junction Temperature	TJ	+150	°C
Storage Temperature	T_{STG}	-55~+150	°C

Note: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

- 2. L = 25mH, I_{AS} = 8A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C
- 3. $I_{SD} \le 8A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$
- 4. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	62.5	°C/W
Junction to Case	θ_{JC}	0.7	°C/W

■ ELECTRICAL CHARACTERISTICS (T_C=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS		•		•	•	•
Drain-Source Breakdown Voltage	BV _{DSS}	I _D =250μA, V _{GS} =0V	800			V
Breakdown Voltage Temperature Coefficient	$\triangle BV_{DSS}/\triangle T_{J}$	Reference to 25°C, I _D =250μA		0.5		V/°C
Drain-Source Leakage Current	I _{DSS}	V _{DS} =800V, V _{GS} =0V V _{DS} =640V, T _C =125°C			10 100	μΑ
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V			±100	nA
ON CHARACTERISTICS		, ==	1	I	1	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=250\mu A$	3.0		5.0	V
Static Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =4A		0.94	1.55	Ω
Forward Transconductance (Note 1)	9 FS	V _{DS} =50V, I _D =4A		5.6		S
DYNAMIC PARAMETERS						
Input Capacitance	C _{ISS}			1580	2050	pF
Output Capacitance	Coss	V _{GS} =0V, V _{DS} =25V, f=1.0MHz		135	175	pF
Reverse Transfer Capacitance	C _{RSS}	7		13	17	pF
SWITCHING PARAMETERS (Note 1, No						
Total Gate Charge	Q_G			35	45	nC
Gate to Source Charge	Q_GS	V_{GS} =10V, V_{DS} =640V, I_{D} =8A		10		nC
Gate to Drain Charge	Q_GD			14		nC
Turn-ON Delay Time	$t_{D(ON)}$			40	90	ns
Rise Time	t_R	V _{DD} =400V, I _D =8A, R _G =25Ω		110	230	ns
Turn-OFF Delay Time	$t_{D(OFF)}$	VDD-400V, ID-6A, ING-2312		65	140	ns
Fall-Time	t_{F}			70	150	ns
SOURCE- DRAIN DIODE RATINGS AND	CHARACTER	RISTICS				
Maximum Continuous Drain-Source Diode Forward Current	Is				8	Α
Maximum Pulsed Drain-Source Diode Forward Current	I _{SM}				32	Α
Drain-Source Diode Forward Voltage	V _{SD}	I _S =8A, V _{GS} =0V			1.4	V
Reverse Recovery Time (Note 1)	t _{RR}	I _S =8A, V _{GS} =0V, dI _F /dt=100A/μs		690		ns
Reverse Recovery Charge (Note 1)	Q_{RR}			8.2		μC

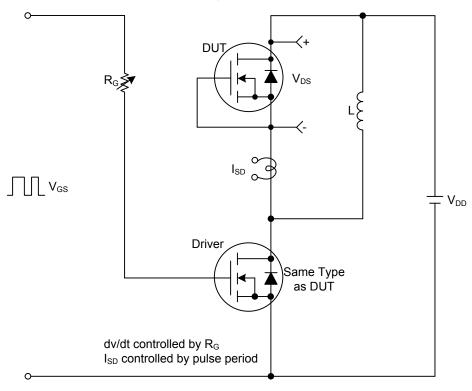
Note: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2%

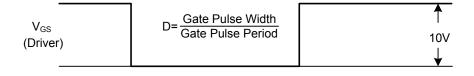
2. Essentially independent of operating temperature

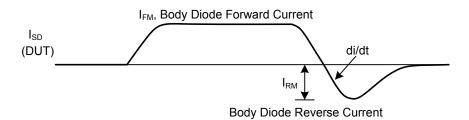


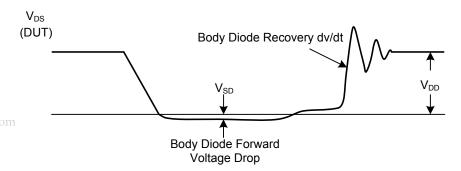
■ TEST CIRCUITS AND WAVEFORMS

Peak Diode Recovery dv/dt Test Circuit & Waveforms



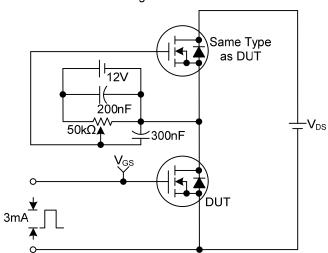




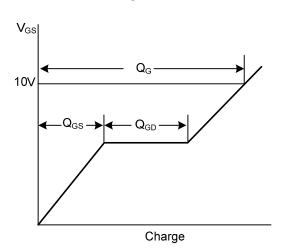


■ TEST CIRCUITS AND WAVEFORMS

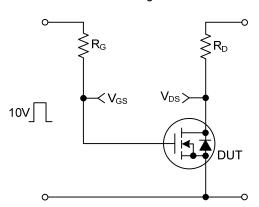
Gate Charge Test Circuit



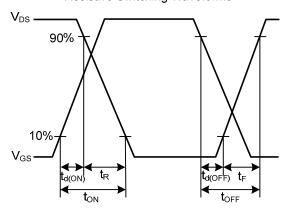
Gate Charge Waveforms



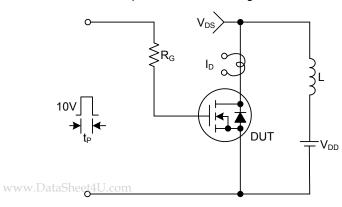
Resistive Switching Test Circuit



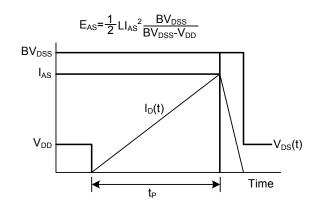
Resistive Switching Waveforms



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms



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